

5A, 20V - 200V Schottky Barrier Surface Mount Rectifier

FEATURES

- Low power loss, high efficiency
- Ideal for automated placement
- Guard ring for overvoltage protection
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.210g (approximately)

| KEY PARAMETERS | | |
|----------------|----------------|------|
| PARAMETER | VALUE | UNIT |
| I_F | 5 | A |
| V_{RRM} | 20 - 200 | V |
| I_{FSM} | 120 | A |
| $T_{J\ MAX}$ | 150 | °C |
| Package | DO-214AB (SMC) | |
| Configuration | Single die | |



DO-214AB (SMC)



| ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted) | | | | | | | | | | | |
|--|--------------|--------------|--------|--------|--------|--------|--------|---------|---------|---------|------------|
| PARAMETER | SYMBOL | SK 52C | SK 53C | SK 54C | SK 55C | SK 56C | SK 59C | SK 510C | SK 515C | SK 520C | UNIT |
| Marking code on the device | | SK 52C | SK 53C | SK 54C | SK 55C | SK 56C | SK 59C | SK 510C | SK 515C | SK 520C | |
| Repetitive peak reverse voltage | V_{RRM} | 20 | 30 | 40 | 50 | 60 | 90 | 100 | 150 | 200 | V |
| Reverse voltage, total rms value | $V_{R(RMS)}$ | 14 | 21 | 28 | 35 | 42 | 63 | 70 | 105 | 140 | V |
| Forward current | I_F | 5 | | | | | | | | | A |
| Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load | I_{FSM} | 120 | | | | | | | | | A |
| Critical rate of rise of off-state voltage | dV/dt | 10,000 | | | | | | | | | V/ μ s |
| Junction temperature | T_J | - 55 to +150 | | | | | | | | | °C |
| Storage temperature | T_{STG} | - 55 to +150 | | | | | | | | | °C |

| THERMAL PERFORMANCE | | | |
|--|-----------------|------------|-------------|
| PARAMETER | SYMBOL | TYP | UNIT |
| Junction-to-lead thermal resistance | $R_{\theta JL}$ | 17 | °C/W |
| Junction-to-ambient thermal resistance | $R_{\theta JA}$ | 50 | °C/W |

| ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted) | | | | | | |
|---|---|---|---------------|------------|------------|-------------|
| PARAMETER | | CONDITIONS | SYMBOL | TYP | MAX | UNIT |
| Forward voltage ⁽¹⁾ | SK52C SK53C SK54C | $I_F = 5\text{A}, T_J = 25^\circ\text{C}$ | V_F | - | 0.55 | V |
| | SK55C SK56C | | | - | 0.75 | V |
| | SK59C SK510C | | | - | 0.85 | V |
| | SK515C SK520C | | | - | 0.95 | V |
| Reverse current @ rated V_R ⁽²⁾ | SK52C SK53C SK54C SK55C SK56C | $T_J = 25^\circ\text{C}$ | I_R | - | 0.5 | mA |
| | SK59C SK510C SK515C SK520C | | | - | 0.3 | mA |
| | SK52C SK53C SK54C | $T_J = 100^\circ\text{C}$ | I_R | - | 20 | mA |
| | SK55C SK56C | | | - | 10 | mA |
| | SK59C SK510C SK515C SK520C | | | - | - | mA |
| | SK52C SK53C SK54C | $T_J = 125^\circ\text{C}$ | I_R | - | - | mA |
| | SK55C SK56C | | | - | - | mA |
| | SK59C SK510C SK515C SK520C | | | - | 5 | mA |

Notes:

1. Pulse test with $PW = 0.3\text{ms}$
2. Pulse test with $PW = 30\text{ms}$

| ORDERING INFORMATION | | |
|------------------------------------|----------------|---------------------|
| ORDERING CODE⁽¹⁾ | PACKAGE | PACKING |
| SK5xC | DO-214AB (SMC) | 3,000 / Tape & Reel |

Notes:

1. "x" defines voltage from 20V(SK52C) to 200V(SK520C)

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

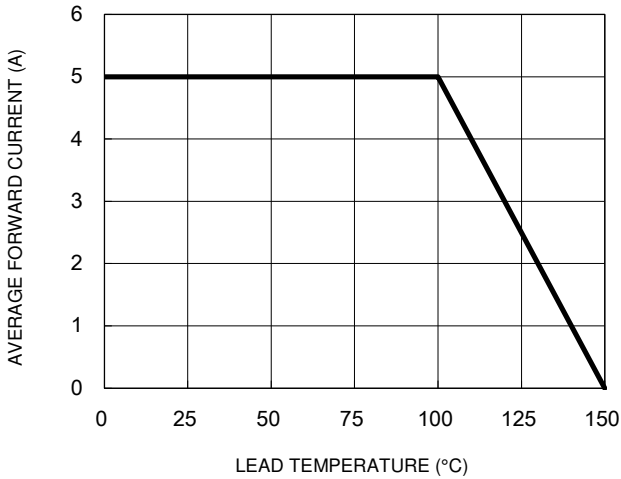


Fig.2 Typical Junction Capacitance

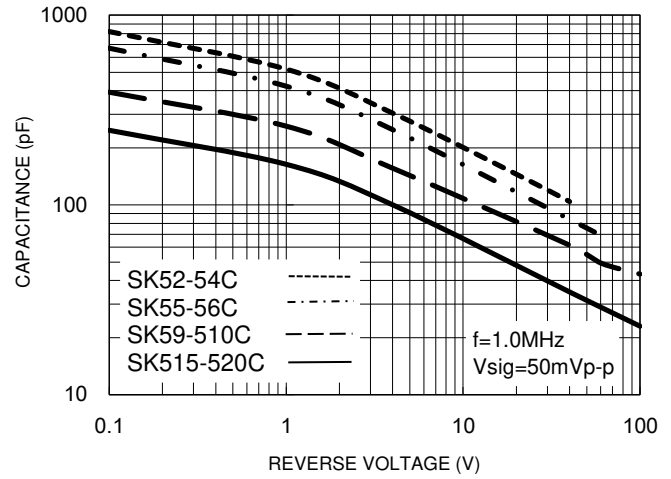


Fig.3 Typical Reverse Characteristics

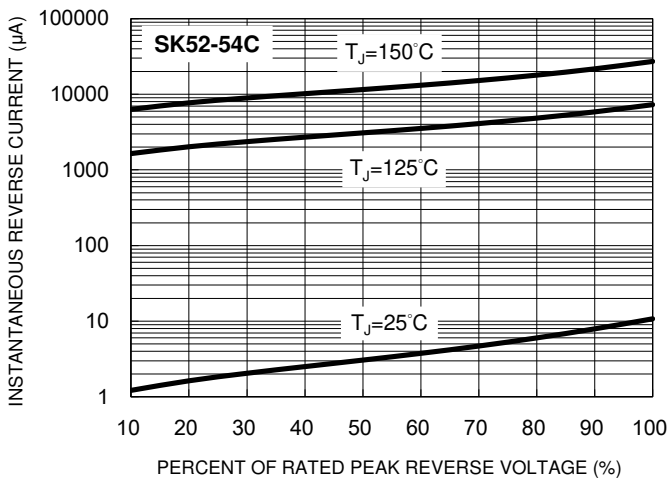


Fig.4 Typical Forward Characteristics

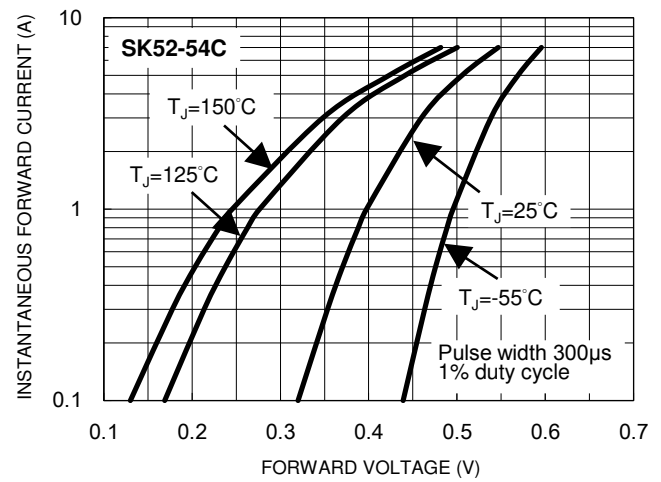


Fig.5 Typical Reverse Characteristics

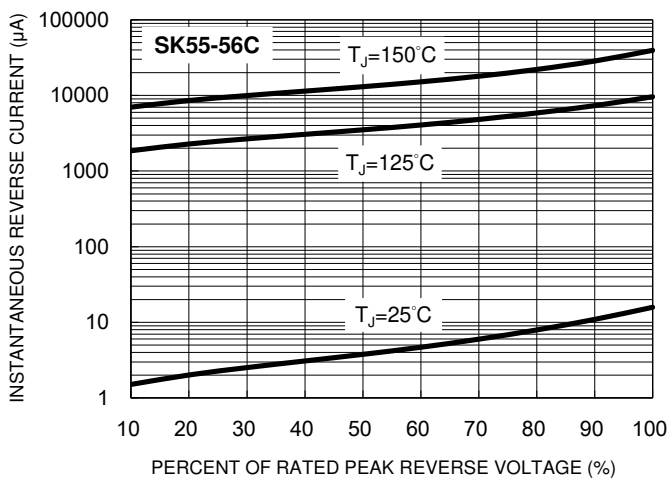
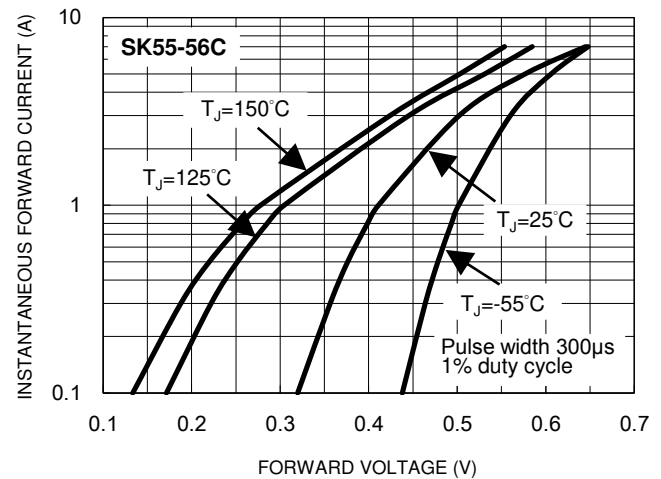


Fig.6 Typical Forward Characteristics



CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.7 Typical Reverse Characteristics

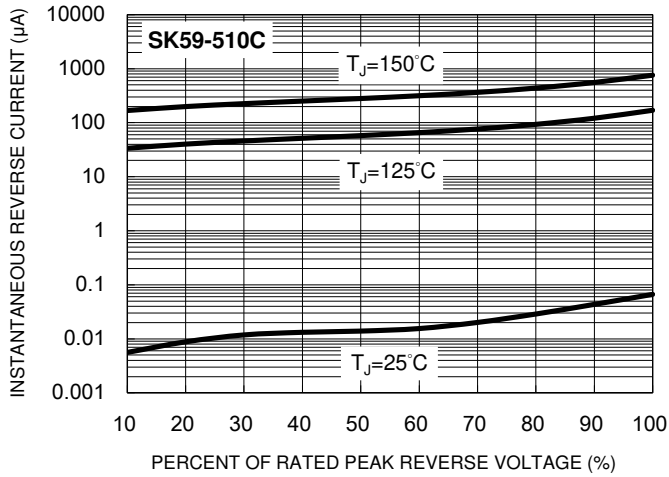


Fig.8 Typical Forward Characteristics

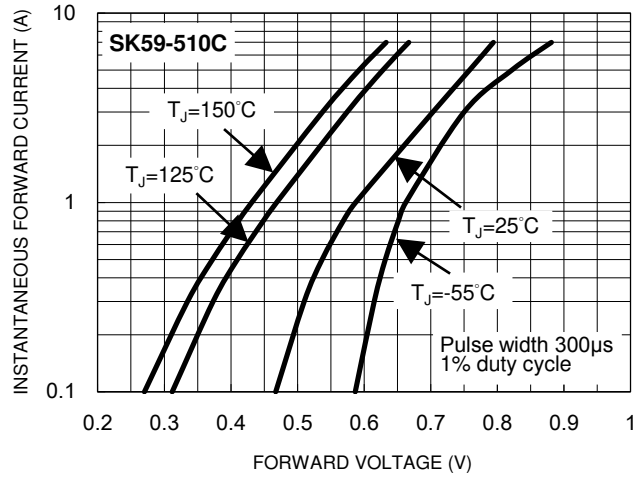


Fig.9 Typical Reverse Characteristics

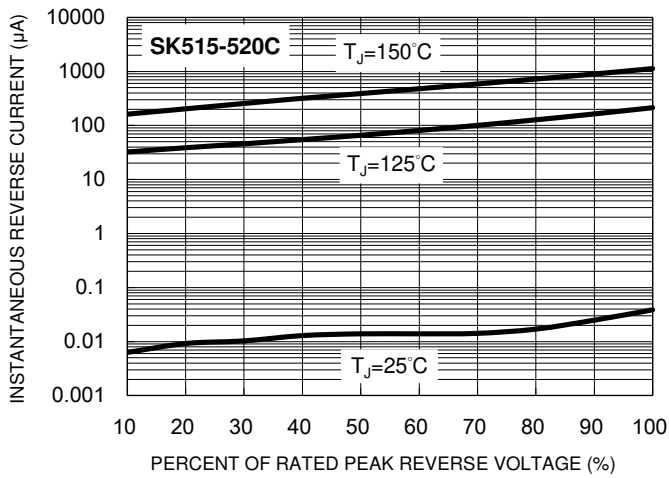


Fig.10 Typical Forward Characteristics

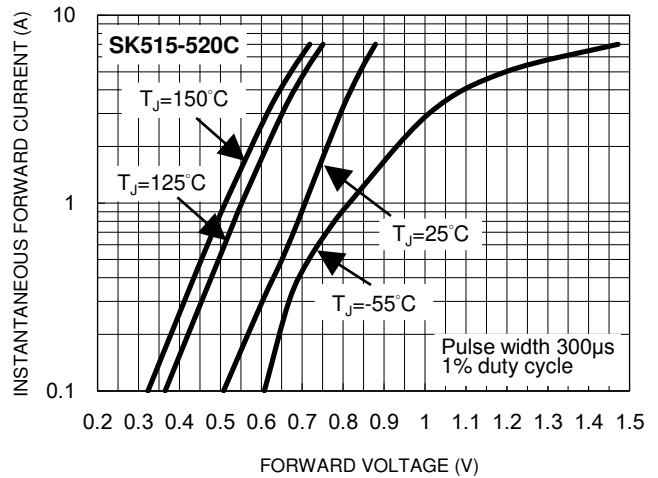
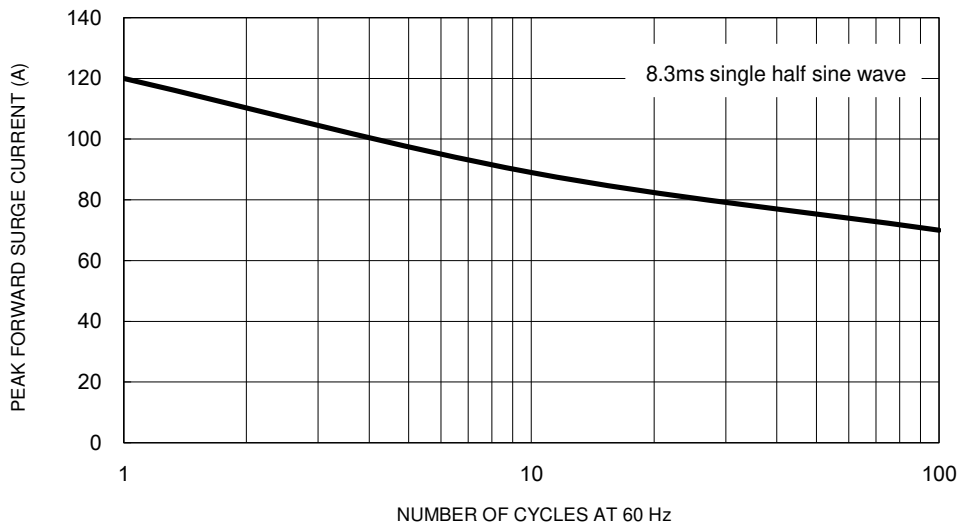


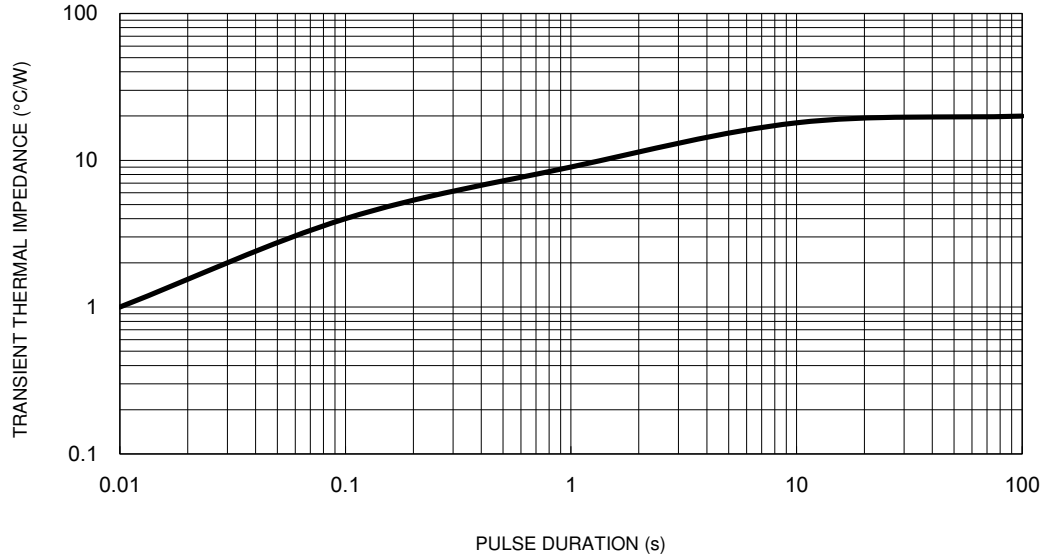
Fig.11 Maximum Non-Repetitive Forward Surge Current



CHARACTERISTICS CURVES

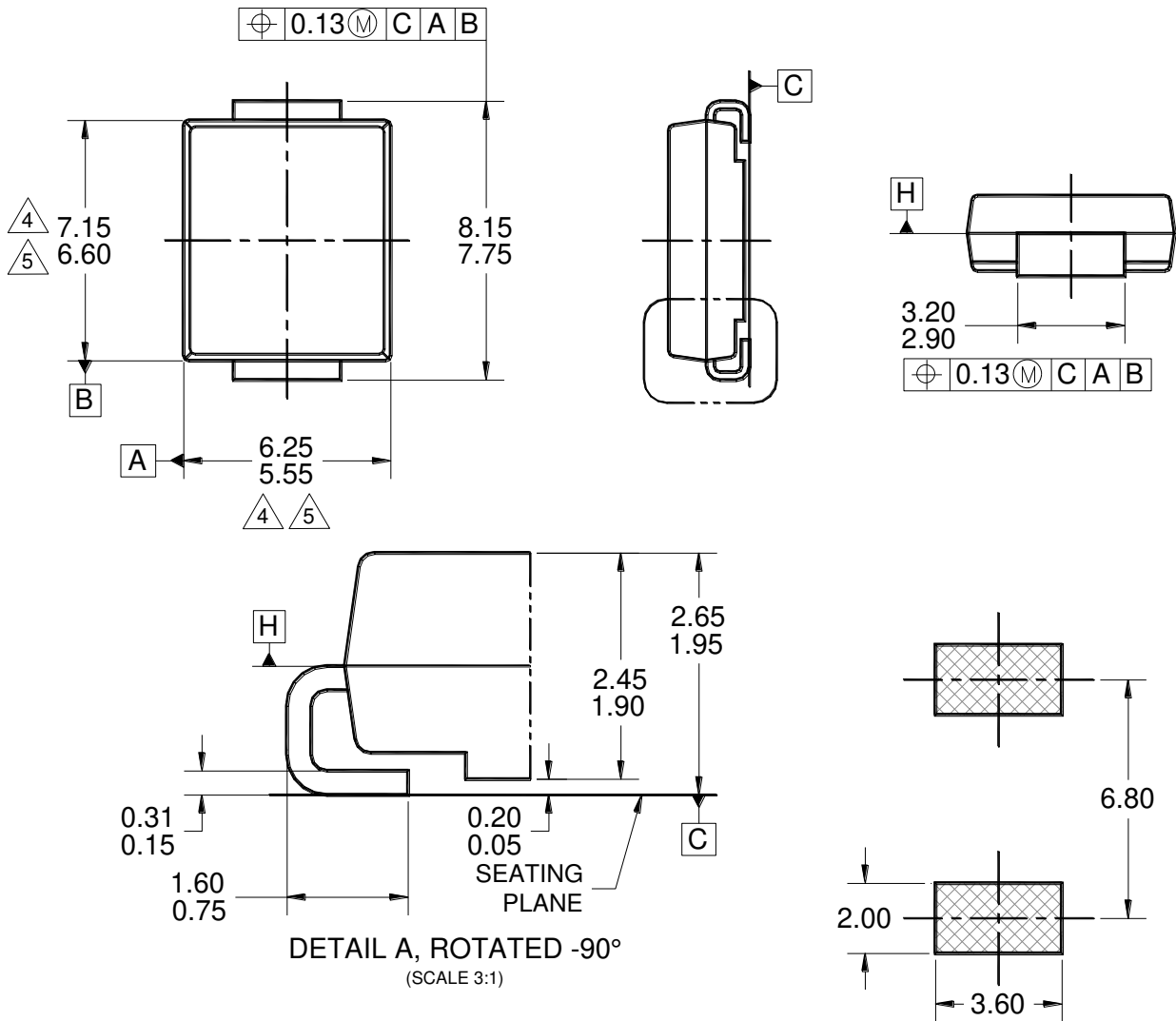
($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.12 Typical Transient Thermal Characteristics

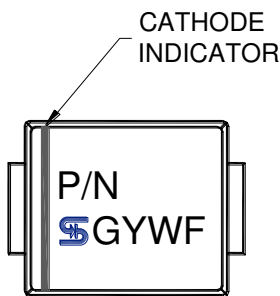


PACKAGE OUTLINE DIMENSIONS

DO-214AB (SMC)



SUGGESTED PAD LAYOUT



MARKING DIAGRAM

P/N = MARKING CODE
 G = GREEN COMPOUND
 YW = DATE CODE
 F = FACTORY CODE

NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PACKAGE OUTLINE REFERENCE: JEDEC DO-214, VARIATION AB, ISSUE D.
4. MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
5. MOLDED PLASTIC BODY LATERAL DIMENSIONS TO BE DETERMINED AT DATUM PLANE H.
6. DWG NO. REF: HQ2SD07-DO214SMC-036 REV A.

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